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## *Editorial / Uvodnik*

Dear reader,

Isn't it amazing how time flies? In the last year, our journal operations and processes ran smoothly and I am grateful to EB members, reviewers and technical support team for their valuable contribution to the success. All papers published are open-access and accessible in WoS, Scopus, DOAJ or on the journal web pages by a single mouse click. Do open-access papers help us in wider dissemination and larger readership? We are tracking the numbers and the trends look promising.

In 2023 we received more than 230 manuscripts, out of which only 20 have been accepted for publication so far, while 35 were out of scope and 94 manuscripts were rejected. The success rate remains low (below 20% in 2023) primarily because we receive many manuscripts that do not meet the quality and scientific originality that we aim at. Citation metrics for 2022 (published in June 2023) improved significantly – JCR IF-2022= 1.20, SNIP-2022=0.418 and CiteScore-2022=1.70. In 2023 we published 1 review scientific papers (on accurate positioning in wireless cellular networks) and 19 original scientific papers.

We commit ourselves to continue serving you as a part of your success in science and engineering and look forward to receiving your future manuscript(s) on our submission page (<http://ojs.midem-drustvo.si/>).

Be productive and efficient! Take care and stay healthy!

Prof. Marko Topič  
Editor-in-Chief

15 March 2024



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